

**LISTING OF CLAIMS:**

1. (Original) An apparatus for supporting an object to be fabricated, wherein the object is supported spaciouly apart from a supporting surface of a chuck comprising:  
a plurality of sliding pockets sunken into the supporting surface of the chuck; and  
a plurality of sliding pads respectively floating-coupled in the sliding pockets such that the sliding pads are spaced apart from the supporting surface in order to provide adaptive support to the object to be fabricated to compensate for the object's expansion and contraction.

2. (Original) The apparatus for supporting an object to be fabricated of claim 1, wherein each of the sliding pockets includes a magnetic pocket body having an internal space that confines a part of the sliding pad to prevent the sliding pad from escaping, and a magnetic base cover spaced apart from a lower part of the sliding pad for enabling the sliding pad to be connected to or disconnected from the pocket body in one direction.

3. (Original) The apparatus for supporting an object to be fabricated of claim 2, wherein the sliding pad includes a sliding body with parts having a magnetic polarity identical to the magnetic polarity of corresponding parts of the pocket body and base cover to allow the sliding pad to move freely in the internal space of the pocket body with no contact to the sliding pocket, and a supporting member installed at a part of an upper surface of the sliding body.

4. (Original) The apparatus for supporting an object to be fabricated of claim 3, wherein the corresponding parts of the sliding pocket and sliding body are made of the same magnetic substance.

5. (Original) The apparatus for supporting an object to be fabricated of claim 3, wherein the sliding pad is in a reverse T shape.

6. (Original) The apparatus for supporting an object to be fabricated of claim 3, wherein the lower part of the pocket body and the base cover are fixed at a predetermined depth into the supporting surface of the chuck.

7. (Original) The apparatus for supporting an object to be fabricated of claim 3, wherein the supporting chuck is an electrostatic chuck for adsorbing an object to be fabricated through the supporting member by electrostatic force.

8. (Original) The apparatus for supporting an object to be fabricated of claim 3, wherein the object to be fabricated is a semiconductor wafer used for manufacturing a plurality of semiconductor devices simultaneously.

9. (Original) A method for fabricating an apparatus for supporting an object to be fabricated, wherein the object is supported spaciouly apart from a supporting surface of a chuck comprising:

sinking a plurality of sliding pockets into the supporting surface of the chuck; and forming a plurality of sliding pads respectively floating-coupled in the sliding pockets such that the sliding pads are spaced apart from the supporting surface of the chuck in order to provide adaptive support to the object to be fabricated to compensate for the object's expansion and contraction.

10. (Original) The method of claim 9, further comprising:  
forming a plurality of accommodation grooves at an upper part of a body of the chuck for accommodating the sliding pocket; and  
sequentially pressing and inserting into the grooves the base cover of the sliding pocket and the pocket body having the sliding pad floating-coupled inside.

11. (Original) The method of claim 10, wherein the body of the chuck is made of a material having a thermal expansion coefficient identical or similar to that of the electrostatic chuck.